ABSTRACT OF THE DISCLOSURE

WAFER CLEANING APPARATUS

A wafer cleaning apparatus used for cleaning a first uncleaned surface of a wafer is provided. The wafer cleaning apparatus includes a case, a spin device, a cover, at least one first spray bar, and at least one exhaust device. The spin device is disposed in the case and used for carrying the wafer and spinning perpendicularly to the ground. The cover is disposed in the case and used for covering the spin device. The first spray bar is disposed at one side of the spin device and used for spraying a volatile cleaning solution onto the first uncleaned surface of the wafer, in which the sprayed volatile cleaning solution is of a bar shape. The exhaust device is disposed on the sidewall of the case.

(FIG. 1)